

What is claimed is:

1. A semiconductor device which comprises external interface terminals and processing circuits, and which is fed with an operating power source when detachably set in a host equipment, wherein:

said external interface terminals include power source feeding terminals, an extraction detecting terminal, and other terminals;

said power source feeding terminals are long enough to keep touching corresponding terminals of the host equipment for, at least, a predetermined time period since separation of said extraction detecting terminal from a corresponding terminal of the host equipment;

said power source feeding terminals are formed to be longer in an extraction direction than said extraction detecting terminal;

said power source feeding terminals are a power source terminal and a ground terminal; and

any power source compensating capacitor is not connected between said power source terminal and said ground terminal.

2. A semiconductor device according to claim 1, wherein decoupling capacitors are connected between said power source terminal and said ground terminal.

3. A semiconductor device according to claim 1, wherein said power source feeding terminals are made longer than said

extraction detecting terminal, also on a side opposite to the extraction direction, and a length which said power source feeding terminals protrude on the opposite side to the extraction direction, beyond said extraction detecting terminal, is smaller than a length which they protrude in the extraction direction.

4. A semiconductor device which comprises external interface terminals and processing circuits, and which is fed with an operating power source when detachably set in a host equipment, wherein:

said external interface terminals include power source feeding terminals, an extraction detecting terminal, and other terminals;

said power source feeding terminals are long enough to touch corresponding terminals of the host equipment for, at least, 1.0 millisecond since separation of said extraction detecting terminal from a corresponding terminal of the host equipment, with respect to an extraction speed of 2.5 meters/second;

said power source feeding terminals are a power source terminal and a ground terminal; and

any power source compensating capacitor is not connected between said power source terminal and said ground terminal.

5. A semiconductor device according to claim 4, wherein decoupling capacitors are connected between said power source

terminal and said ground terminal.

6. A semiconductor device according to claim 5, wherein said power source feeding terminals are formed to be longer in an extraction direction than said extraction detecting terminal.

7. A semiconductor device according to claim 6, wherein said power source feeding terminals are made longer than said extraction detecting terminal, also on a side opposite to the extraction direction, and a length which said power source feeding terminals protrude on the opposite side to the extraction direction, beyond said extraction detecting terminal, is smaller than a length which they protrude in the extraction direction.

8. A semiconductor device which comprises external interface terminals and processing circuits, and which is fed with an operating power source when detachably set in a host equipment, wherein:

said external interface terminals are arranged in two rows in a direction crossing an extraction direction, and they include power source feeding terminals, an extraction detecting terminal, and other terminals;

said power source feeding terminals are long so as to extend from the first row over to the second row;

said power source feeding terminals are a power source terminal and a ground terminal; and

any power source compensating capacitor is not connected between said power source terminal and said ground terminal.

9. A semiconductor device according to claim 8, wherein decoupling capacitors are connected between said power source terminal and said ground terminal.